

Light-Emitting Diodes

3rd edition

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ISBN: 978-0-9 863826-6-6

Publisher: E. Fred Schubert

Year: 2018

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The 1st edition of the book “Light-Emitting Diodes” was published in 2003. The 2nd edition was published in 2006. The current 3rd edition of the book is a substantial expansion of the second edition and has 37 chapters. The book includes a thorough discussion of white light-emitting diodes (LEDs), phosphor materials used in white LEDs, packaging technology, and the various efficiencies and efficacies encountered in the context of LEDs. The background of light, color science, and human vision is provided as well. The fully colored illustrations of the 3rd edition are undoubtedly beneficial given the prominent role of light and color in the field of LEDs. The book is a comprehensive discussion of the LED, particularly its semiconductor physics, electrical, optical, material science, thermal, mechanical, and chemical foundations. The 3rd edition is published in electronic format in order to make the book affordable and easily accessible to a wide readership.

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